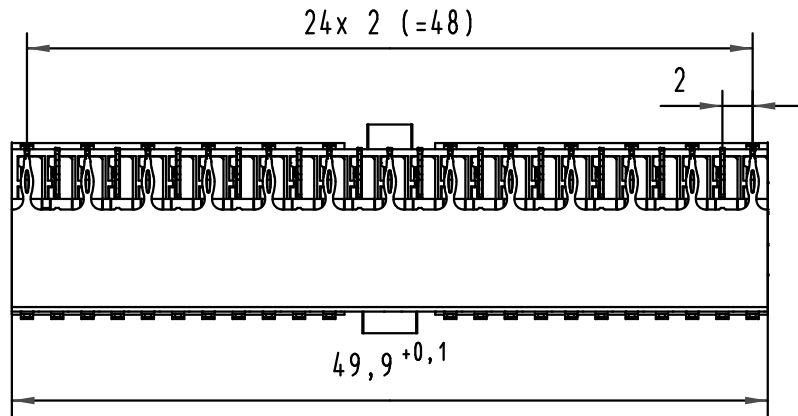
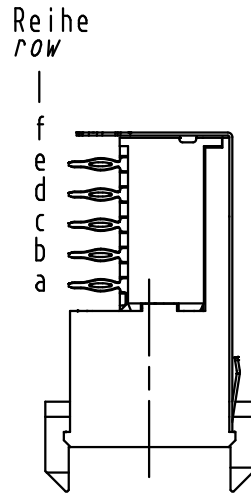
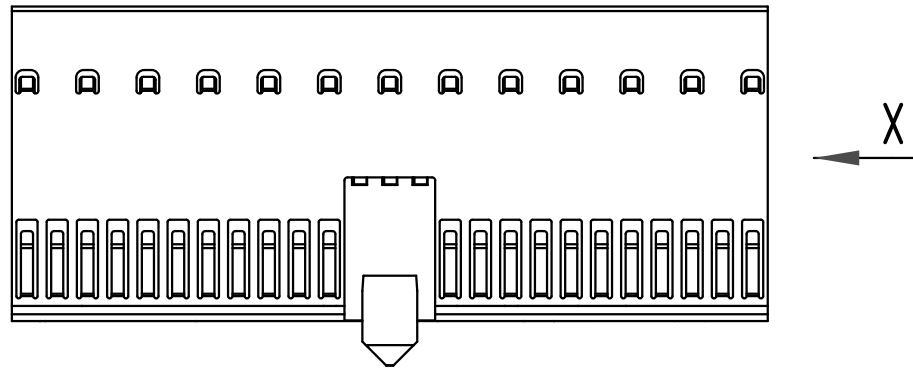
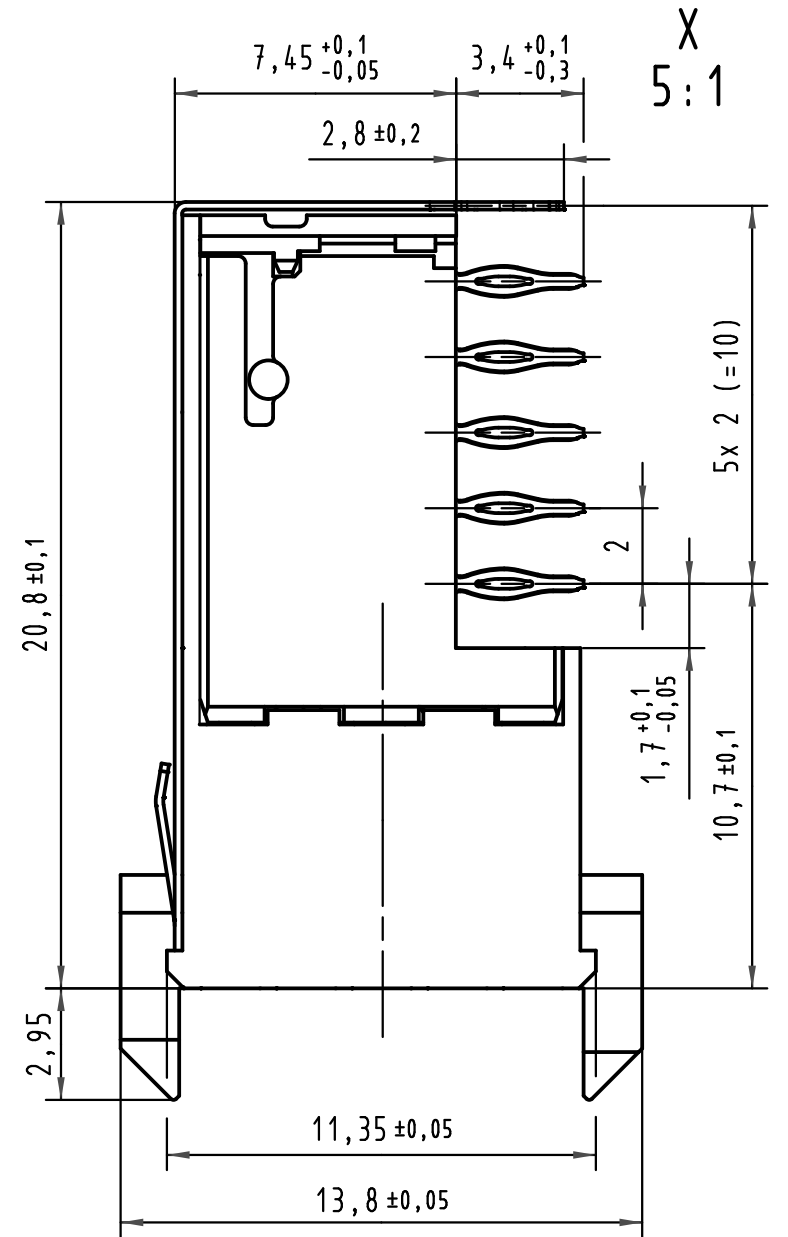
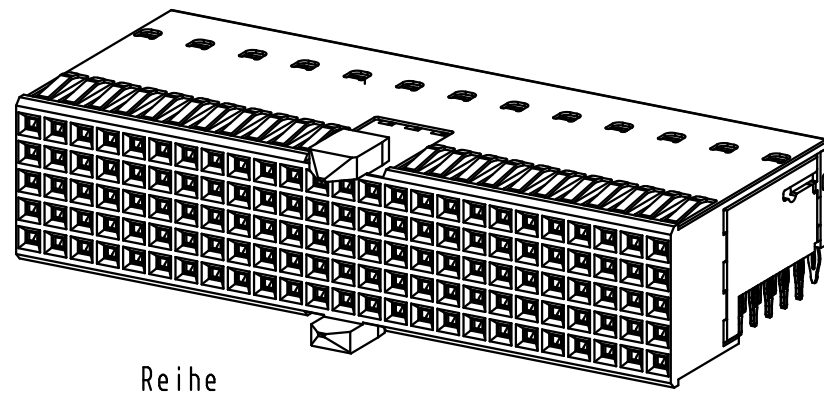
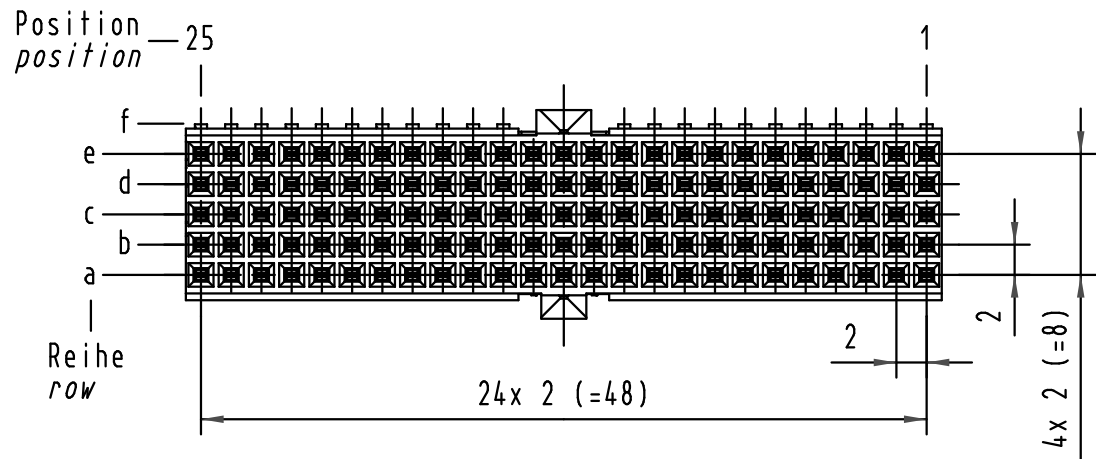
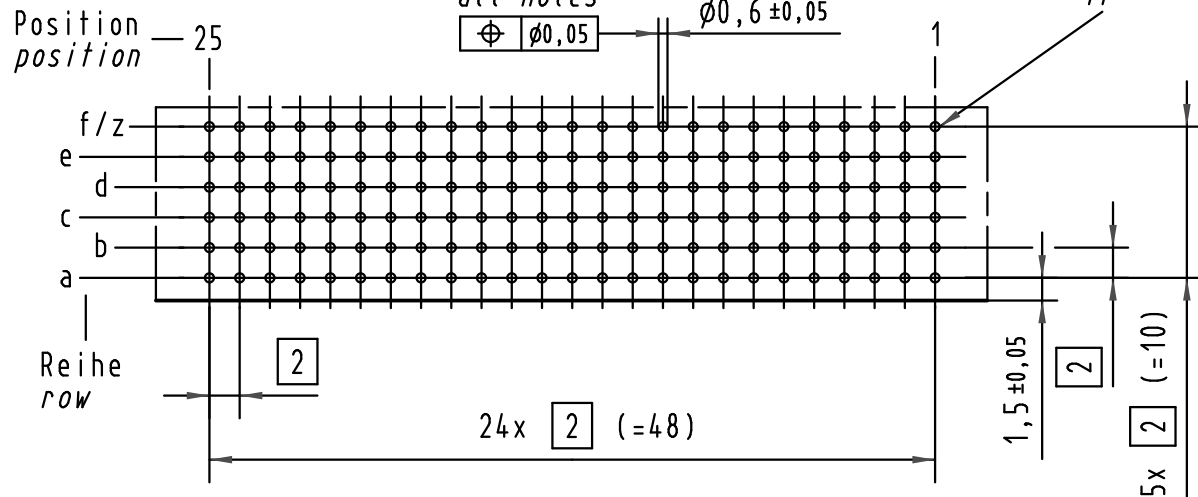


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**Lochbild
board drillings**



alle Löcher
all holes
⊕ $\phi 0,05$ $\phi 0,6 \pm 0,05$

Von f/z/1 aus, jedes 2.
Loch f. obere Abschirmung
from f/z/1, each 2nd
hole f. upper shielding

Bohrlochdurchmesser: $\phi 0,7 \pm 0,02$ mm
Lochdurchmesser (mit Oberfläche): $\phi 0,6 \pm 0,05$ mm
drill hole dia.: $\phi 0,7 \pm 0,02$ mm
through hole dia. (after plating): $\phi 0,6 \pm 0,05$ mm

17 35 125 <u>4</u> 102	—	min. 0,76 μ m (30 μ m) Au über/over min. 1,27 μ m (50 μ m) Ni
17 35 125 <u>2</u> 102	2	Au über/over Ni
17 35 125 <u>1</u> 102	1	Au über/over Ni
Bestell-Nr. part-no.	Anforderungsstufe nach IEC performance level acc. to IEC	Kontaktoberfläche contact plating

			Techn. Character.			Nicht tolerierte Maß/Free size tolerances IEC 61076-4-101		
			Dat.		Name		Maßstab/Scale	
			Detail. 01.06.01		Hm		2:1 (5:1)	
			Insp. 01.06.01		Ko		har-bus HM Federleiste, Typ AB-25, 125 pol. mit Schirmblech Reihe-f har-bus HM female connector, type AB-25, 125 pol. with shield row-f	
35456 01.12.08 TD			Stand.				TB 17 35 125 x102	
32387 19.11.04 HL							Blatt/page	
27619							Sub.	
Mod. Dat. Name			HARTING Electronics GmbH & Co. KG D-32339 ESPELKAMP					